SDLS047 - DECEMBER 1983 - REVISED MARCH 1988

- Operation from Very Slow Edges
- Improved Line-Receiving Characteristics
- High Noise Immunity

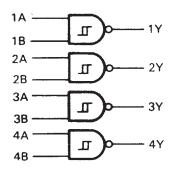
description

Each circuit functions as a 2-input NAND gate, but because of the Schmitt action, it has different input threshold levels for positive (V_{T+}) and for negative going (V_{T-}) signals.

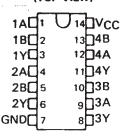
These circuits are temperature-compensated and can be triggered from the slowest of input ramps and still give clear, jitter-free output signals.

The SN54132, SN54LS132, and SN54S132 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74132, SN74LS132, and SN74S132 are characterized for operation from 0°C to 70°C.

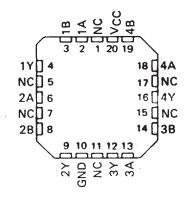
logic diagram (positive logic)



SN54132, SN54LS132, SN54S132 . . . J OR W PACKAGE SN74132 . . . N PACKAGE SN74LS132, SN74S132 . . . D OR N PACKAGE (TOP VIEW)

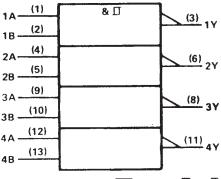


SN54LS132, SN54S132 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection

logic symbol†

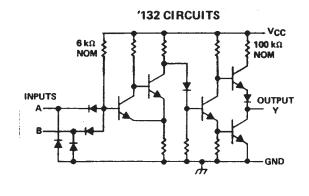


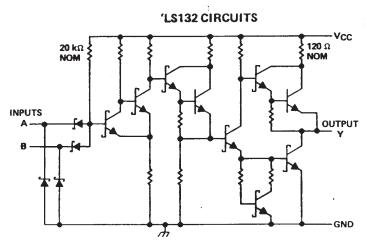
positive logic: $Y = \overline{AB}$ or $Y = \overline{A} + \overline{B}$

Pin numbers shown are for D, J, N, and W packages.

[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

schematics





'S132 CIRCUITS VCC 50 \(\Omega \) NOM INPUTS A GND

Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: '132, 'S132	5.5 V
'LS132	
Operating free-air temperature: SN54'	– 55° C to 125°C
SN74'	0°C to 70°C
Storage temperature range	— 65°C to 150°C

NOTE 1: Voltages values are with respect to network ground terminal.



recommended operating conditions

			SN5413	2		SN7413	2	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
Іон	High-level output current			- 0.8			- 0.8	mA
IOL	Low-level output current			16			16	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDIT	rions†	MIN	TYP‡	MAX	UNIT
V _{T+}	V _{CC} = 5 V			1.5	1.7	2	V
v _{T-}	V _{CC} = 5 V			0.6	0.9	1.1	V
V _{hys} (V _{T+} -V _{T-})	V _{CC} = 5 V			0.4	0.8		V
ViK	V _{CC} = MIN,	I _I = - 12 mA				- 1.5	V
VOH	V _{CC} = MIN,	V ₁ = 0.6 V,	t _{OH} = - 0.8 mA	2.4	3.4		V
VOL	V _{CC} = MIN,	V ₁ = 2 V,	IOL = 16 mA		0.2	0.4	V
I _{T+}	V _{CC} = 5 V,	V ₁ = V _{T+}			- 0.43		mΑ
1 _T _	V _{CC} = 5 V,	Λ1 = Λ ^L			- 0.56		mA
l ₁	V _{CC} = MAX,	V ₁ = 5.5 V				1	mA
ΊΗ	V _{CC} = MAX,	V ₁ = 2.4 V			-	40	μА
li L	V _{CC} = MAX,	V _{IL} = 0.4 V			- 0.8	- 1.2	mA
los§	V _{CC} = MAX			- 18	•	- 55	mA
ГССН	V _{CC} = MAX				15	24	mA
ICCL	V _{CC} = MAX				26	40	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN TYP	MAX	UNIT
^t PLH	Anv		$R_1 = 400 \Omega$	C ₁ = 15 pF	15	22	กร
^t PHL	Any	ī	H_ = 400 12,	γορε	15	22	ns

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time.

SN54LS132, SN74LS132 QUADRUPLE 2-INPUT POSITIVE-NAND SCHMITT TRIGGERS

SDLS047 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

		S	N54LS1	32	S	SN74LS132			
		MIN	NOM	MAX	MIN	MOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
ЮН	High-level output current			- 0.4			-0.4	mA	
IOL	Low-level output current		***	4			8	mA	
TA	Operating free-air temperature	55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST COND	-: ou ot	S	N54LS1	32	SI	N74LS1	32	UNIT
PANAMETER		TEST CONDI	TIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
V _{T+}	V _{CC} = 5 V			1.4	1.6	1.9	1.4	1.6	1.9	V
V _T _	V _{CC} = 5 V			0.5	0.8	1	0.5	8.0	1	V
V _{hys} (V _{T+} ~V _{T-})	V _{CC} = 5 V		-	0.4	0.8		0.4	0.8		٧
VIK	V _{CC} = MIN,	I _I = - 18 mA				- 1.5			- 1.5	V
Voн	V _{CC} = MIN,	V ₁ = 0.5 V,	IOH = - 0.4 mA	2.5	3.4		2.7	3.4		٧
VOL	V _{CC} = MIN,	V _I = 1.9 V	IOL = 4 mA		0.25	0.4		0.25	0.4	v
VOL	A C.C 141114'	V - 1.5 V	IOL = 8 mA					0.35	0.5	
IT+	V _{CC} = 5 V,	V _I = V _{T+}		-	- 0.14		-	- 0.14		mA
IT_	V _{CC} = 5 V,	Vi = VT_		-	- 0.18			- 0.18		mA
Ц	V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	mA
ИН	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	μА
IL	V _{CC} = MAX,	V _{IL} = 0.4 V				- 0.4			- 0.4	mA
los §	V _{CC} = MAX			- 20		- 100	- 20		- 100	mA
Iссн	V _{CC} = MAX				5.9	11		5.9	11	mA
¹ CCL	V _{CC} = MAX				8.2	14		8.2	14	mA

 $^{^{\}dagger}$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see figure 1)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST COM	IDITIONS	MIN	TYP	MAX	UNIT
	^t PLH	Anv	Y	$R_1 = 2 k\Omega$	C ₁ = 15 pF		15	22	ns
-	^t PHL_		<u>'</u>	1,5 2,442,	OF = 19 bt		15	22	ns

[‡] All typical values are at V_{CC} = 5 V, T_A = 25° C.

[§] Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second

SN54S132, SN74S132 QUADRUPLE 2-INPUT POSITIVE-NAND SCHMITT TRIGGERS

SDLS047 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

			SN54S1	32		UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
Іон	High-level output current			– 1			– 1	mA
IOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDIT	uovet		SN54S1	32	:	SN74S1	32	UNIT
PARAMETER		TEST CONDIT	ION2.	MIN	TYP‡	MAX	MIN	TYP‡	MAX	ONT
V _{T+}	V _{CC} = 5 V			1.6	1.77	1.9	1.6	1.77	1.9	٧
V _T _	V _{CC} = 5 V			1.1	1.22	1.4	1.1	1.22	1.4	٧
V _{hys} (V _{T +} -V _{T -})	V _{CC} = 5 V			0.2	0.55		0.2	0.55		٧
VIK	V _{CC} = MIN,	I ₁ = - 18 mA				- 1.2			- 1.2	V
Voн	V _{CC} = MIN,	V ₁ = 1.1 V,	IOH = - 1 mA	2.5	3.4		2.7	3.4		٧
VOL	V _{CC} = MIN,	$V_1 = 1.9 V$,	IOL = 20 mA			0.5			0.5	٧
I _{T+}	V _{CC} = 5 V,	V1 = VT+			- 0.9			- 0.9		mA
1T_	V _{CC} = 5 V,	VI = VT_			- 1.1			- 1.1		mA
lį	V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
ЧН	V _{CC} = MAX,	V ₁ = 2.7 V				50			50	μA
115	V _{CC} = MAX,	V _{1L} = 0.5 V				- 2			- 2	mΑ
los§	V _{CC} = MAX			- 40		- 100	- 40		– 100	mΑ
ССН	V _{CC} = MAX				28	44		28	44	mA
ICCL	V _{CC} = MAX				44	68		44	68	mA

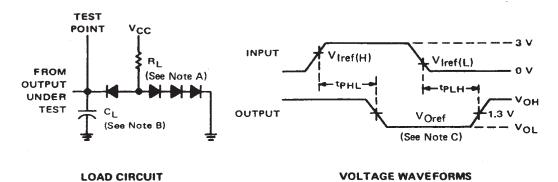
 $^{^\}dagger$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONI	DITIONS	MIN	TYP	MAX	UNIT
^t PLH	A or B	~	$R_1 = 280 \Omega$	C ₁ = 15 pF		7	10.5	กร
t _{PHL}	70,0	'	11 - 200 14,	O[- 13 br		8.5	13	ns

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. § Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. All diodes are 1N3064 or equivalent.

B. C_L includes probe and jig capacitance.

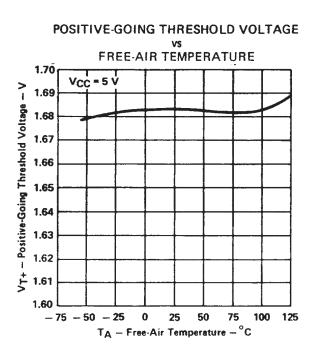
C. Generator characteristics and reference voltages are:

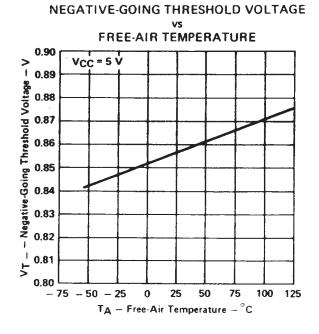
	G	enerator C	haracteris	tics	Ref	erence Voltag	es
	Zout	PRR	t _r	tf	VI ref(H)	VI ref(L)	VO ref
SN54'/SN74'	50	1 MHz	10 ns	10 ns	1.7 V	0.9 V	1.5 V
SN54LS'/SN74LS'	50	1 MHz	15 ns	6 ns	1.6 V	0.8 V	1.3 V
'S132	50	1 MHz	2.5 ns	2.5 ns	1.8 V	1.2 V	1.5 V

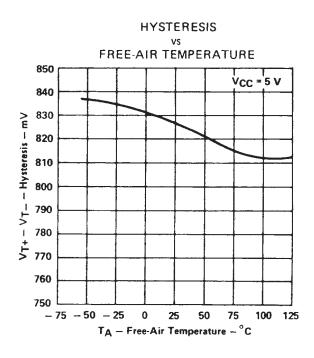
FIGURE 1

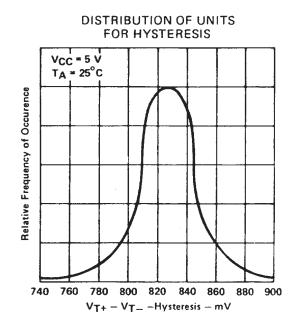


TYPICAL CHARACTERISTICS OF '132 CIRCUITS

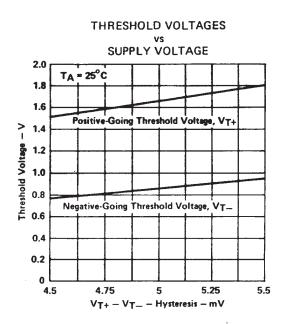


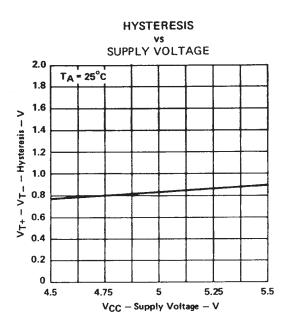


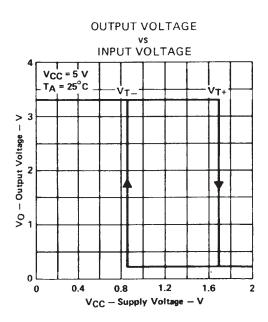




TYPICAL CHARACTERISTICS OF '132 CIRCUITS





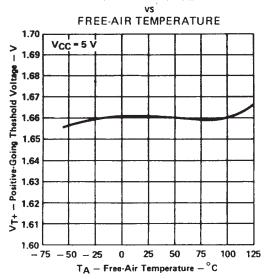


 $^{^{\}dagger}$ Data for temperatures below 0° C and 70° C and supply below 4.75 V and above 5.25 V are applicable for SN54132 only.

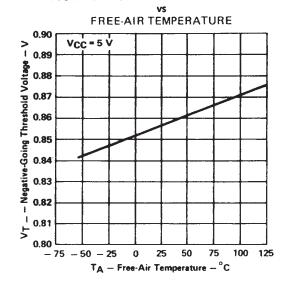


TYPICAL CHARACTERISTICS OF 'LS132 CIRCUITS

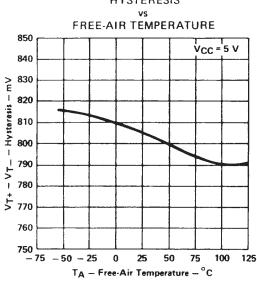
POSITIVE-GOING THRESHOLD VOLTAGE



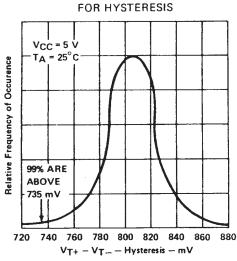
NEGATIVE-GOING THRESHOLD VOLTAGE



HYSTERESIS



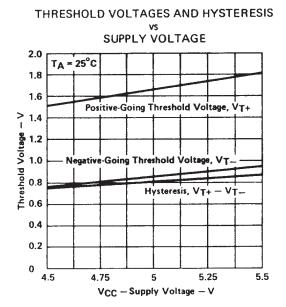
DISTRIBUTION OF UNITS

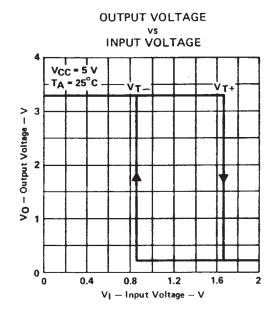


Data for temperatures below 0°C and above 70°C and supply voltages below 4.75 V and above 5.25 V are applicable for SN54LS132 only.

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TYPICAL CHARACTERISTICS OF 'LS132 CIRCUITS

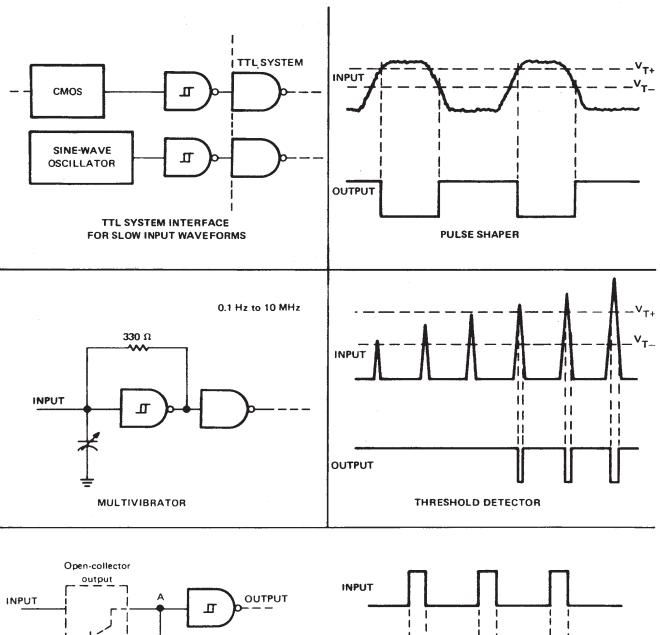


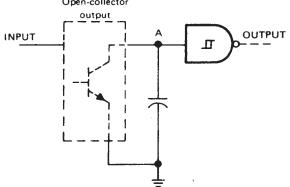


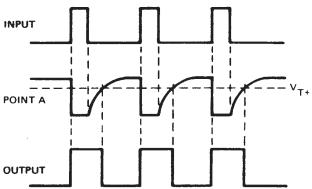
[†] Data for temperatures below 0°C and above 70°C and supply voltages below 4.75 V and above 5.25 V are applicable for SN54LS132 only.



TYPICAL APPLICATION DATA







PULSE STRETCHER



25-Jan-2012

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
7600401CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
7600401DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Call TI	
7600401DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Call TI	
JM38510/31303BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
JM38510/31303BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/31303BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/31303BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54132J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN54132J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN54LS132J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54LS132J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54S132J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54S132J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN74132N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74132N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74132N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74132N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74LS132D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74LS132DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74LS132J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74LS132N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS132N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS132N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74LS132N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74LS132NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS132NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS132NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS132NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74S132N	NRND	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S132N	NRND	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S132N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74S132N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	





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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74S132NE4	NRND	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S132NE4	NRND	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SNJ54132J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SNJ54132J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SNJ54LS132FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS132FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS132J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54LS132J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54LS132W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ54LS132W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ54S132FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54S132FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54S132J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54S132J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54S132W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ54S132W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM



www.ti.com 25-Jan-2012

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OTHER QUALIFIED VERSIONS OF SN54132, SN54LS132, SN54S132, SN74LS132, SN74LS132, SN74S132:

• Catalog: SN74132, SN74LS132, SN74S132

Military: SN54132, SN54LS132, SN54S132

NOTE: Qualified Version Definitions:

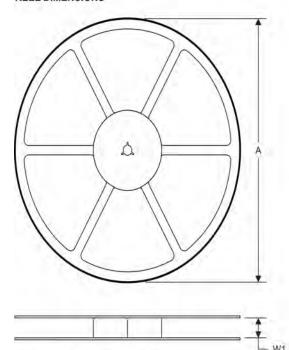
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

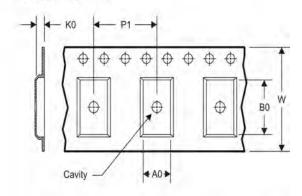
www.ti.com 14-Jul-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
КО	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS132DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS132NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

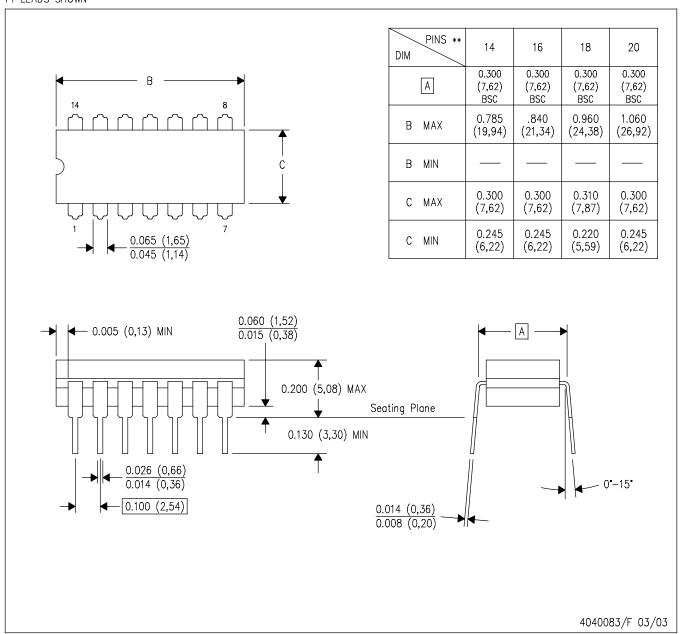
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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS132DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS132NSR	SO	NS	14	2000	367.0	367.0	38.0

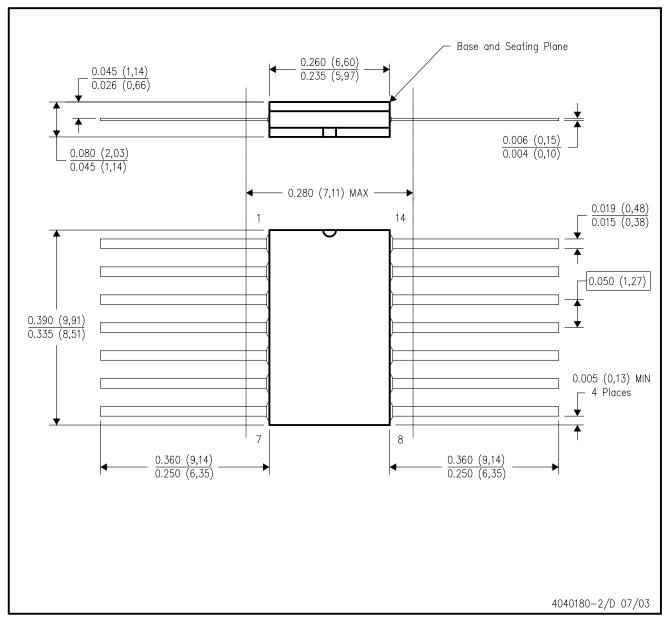
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



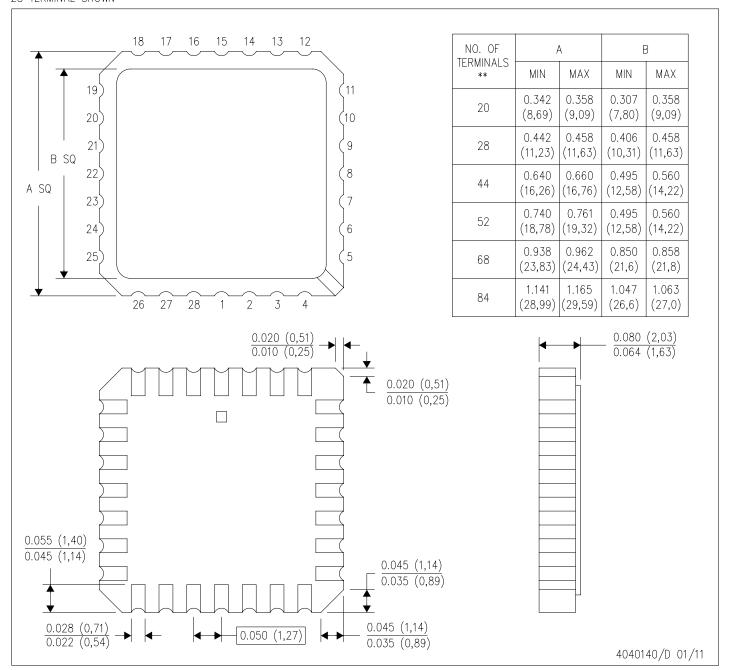
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



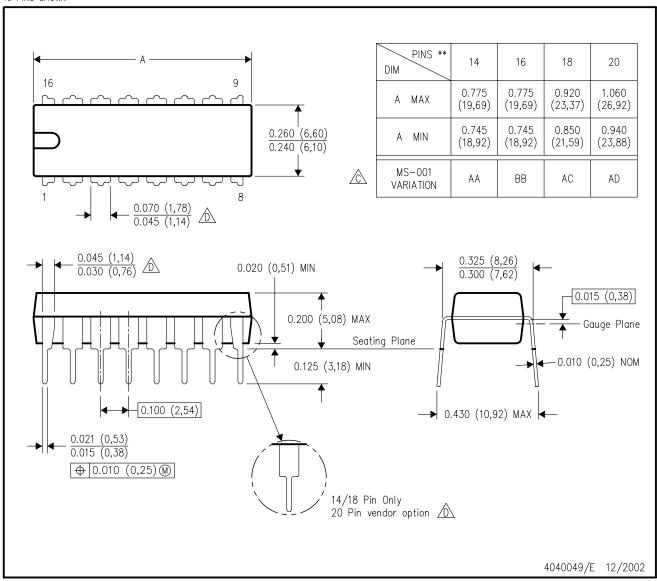
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

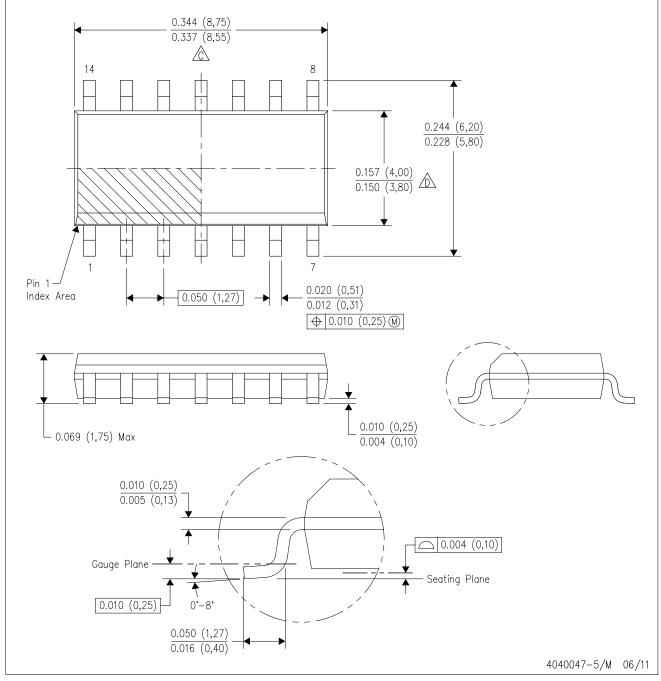


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

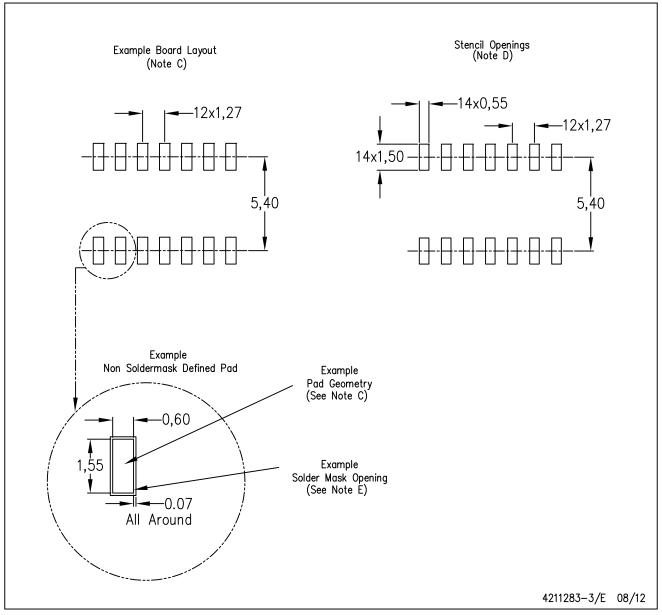


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



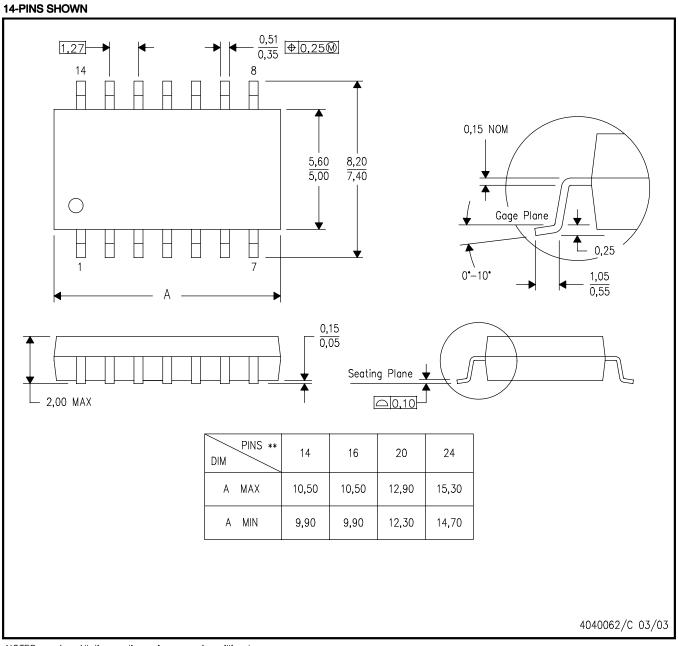
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE



- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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